

Experimental Particle Physics

50 µm Thick LGAD: Electrical Characterisation & Gain Measurement



CSIC

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Introduction

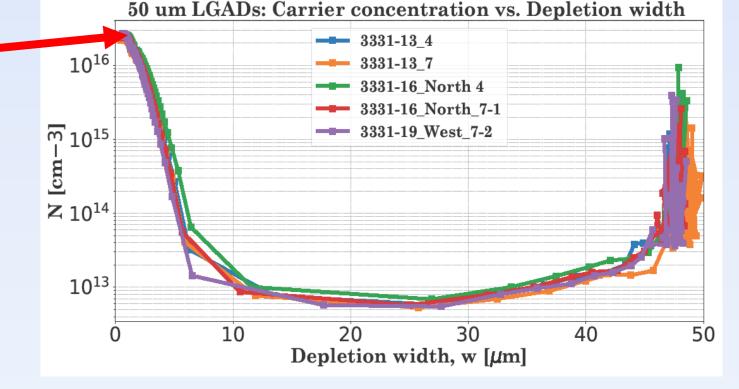
- *****The Low-Gain Avalanche Detectors (LGADs) operate with an internal charge multiplication [1].
- ✤ Higher signal output compared to standard diode for MIP excellent timing resolution.
- *****Identified as one of the candidates for the High-Granularity **Timing Detector for ATLAS Phase-II upgrade [2].**
- Typical structure: n+/p/p-/p+ on p-type high resistivity substrate [3].
- * Reports the electrical characteristics & gain of 50 µm thick LGADs with various gain implant doses.

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| Gain Doping cond | | 50 um LGADs: Carrier conc | | | |
|-------------------|---|---------------------------|------------------|----|--------------------------------|
| Device | Peak (10 ¹⁶ cm ⁻³) | : | 10 ¹⁶ | | 3 331- 3 331- |
| 3331-19_West_7-2 | 2.72 | - | - 15 | | |
| 3331-16_North_7-1 | 2.61 | [cm-3 | 1015 | | |
| 3331-16_North-4 | 2.46 | Z | 1014 | | |
| 3331-13_7 | 2.37 | | 10 ¹³ | | |
| 3331-13-4 | 2.44 | | | 10 | 20 |
| | | | 0 | 10 | 20 Depletion w |

C-V Measurement Summary

| | | V | | | | |
|---|---|---|---|--|---|--|
| | LGADs | LGADs Pixel Size (mm ²) + JTE(µm) | | C _{fd} (pF/mm ²) | Depletion Width, d (µm) | |
| | 3331-19_West_2-2 | (0.22 x 0.22) + 10 | 30.31 | 0.29 | 47.02 ± 0.88 | |
| | 3331-19_West_7-2 | $(0.5 \ge 0.5) + 10$ | 30.95 | 0.82 | 47.71 ± 0.49 | |
| | 3331-16_North_2 | (0.22 x 0.22) + 10 | 26.24 | 0.31 | 47.77 ± 0.76 | |
| | 3331-16_North_4 | $(0.5 \ge 0.5) + 20$ | 27.62 | 0.96 | $\textbf{47.95} \pm \textbf{0.18}$ | |
| | 3331-16_North_7-1 | $(0.5 \ge 0.5) + 10$ | 28.68 | 0.91 | 47.97 ± 0.25 | |
| | 3331-16_East_38 | $(1.0 \ge 1.0) + 10$ | 28.35 | 2.98 | 47.96 ± 0.37 | |
| | 3331-13_2 | $(0.22 \ge 0.22) + 10$ | 26.64 | 0.29 | 47.91 ± 0.90 | |
| | 3331-13_4 | $(0.5 \ge 0.5) + 20$ | 28.36 | 0.83 | 47.83 ± 0.37 | |
| | 3331-13-7 | $(0.5 \ge 0.5) + 10$ | 28.30 | 0.86 | 49.04 ± 0.37 | |
| F | Gain Measurement | | | TCT MIP Calibration Setup | | |
| | Vbias: Keithley 2410 90% Beam Expander DUT (90:10 Vbias: Keithley Vbias: Keithley | Motion troller: llab ntrol ment of DUT | Sr-90 MIP? LGAD Scintillation Detection Laser Power a | Osc. Trigger: Scintillator + 'AND' qualifer LGAD MIP events: Record signal on LGAD tor adjusted @ 55.8% ≈ 1 MIP | | |
| | 10% Beam Monitor (PIN diode from wafer 3331-19) Softwares IR or Red Laser Laser Trigger Softwares Laser Laser Trigger Surce Normalised QDut = QDut/QbeamMonitor Gain : Normalised QLGAD Normalised QRef. At Full depletion | | 140 | Fit Output Entries Mean 126.9 ± 5 26.9 ± 5 27.01 352.5 352.5 3 | 3.58 / 132 0.26 0.40 | |
| | Laser Source Normalised Q _{Dut} = | Trigger controller Mormalised QLGAD Gain : | 60 40 20 | $MPV_{MIP} \approx 91 \text{m}$ | 5 0 0 0 0 0 0 0 0 0 0 0 0 0 | |



Al layer

180

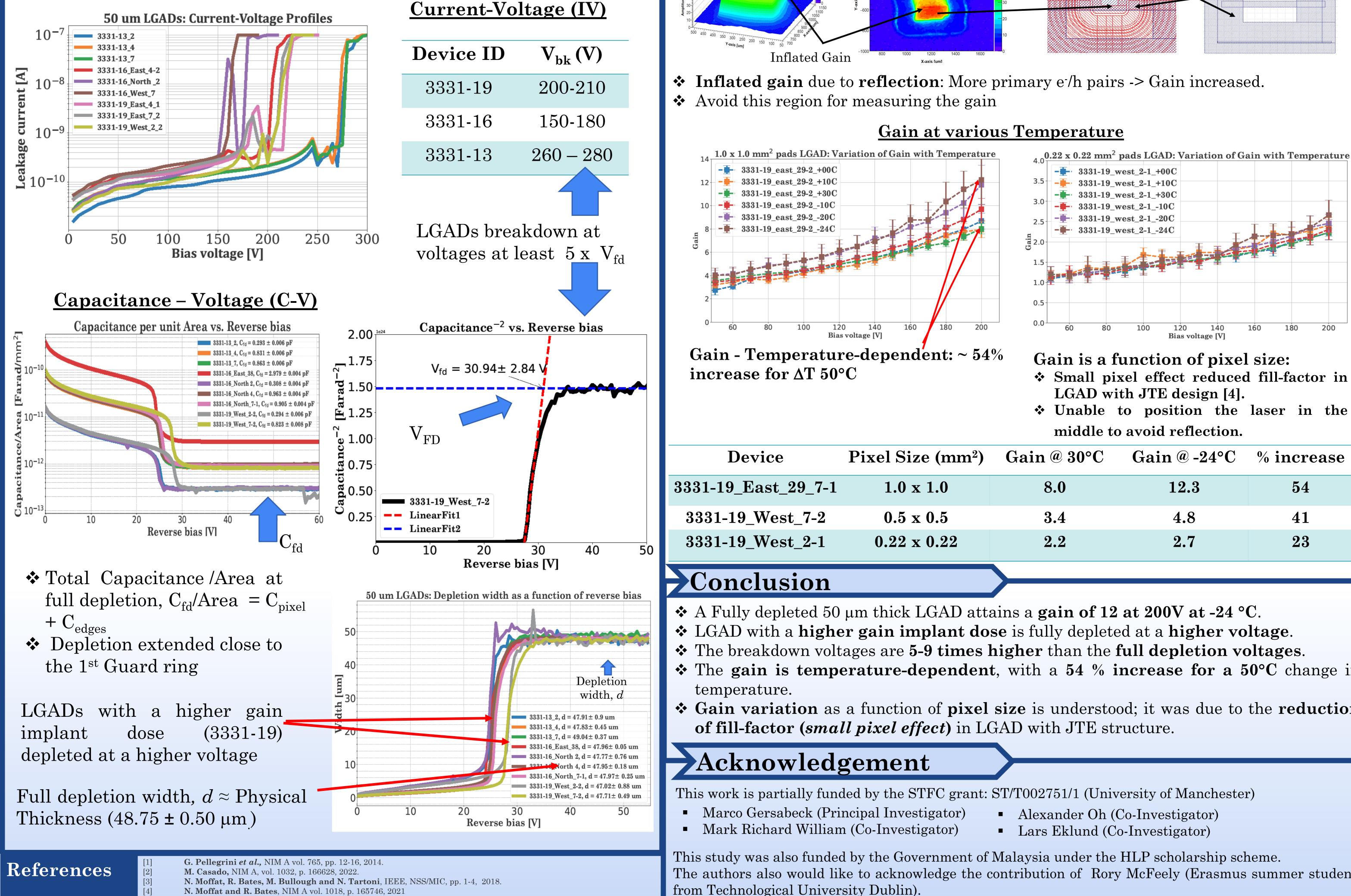
54

200

| Materials and Methods | | | | | |
|-----------------------|------------|--|-------------------------------------|---------------------------------------|--|
| The LGADs | | n+ Cathode JTE P-type (π) substrate (10kohm cm) | | | |
| Wafer ID | Device ID | Pixel Size (mm²) + JTE (μm) | Electrical Characterisation | Gain Measurement | |
| 3331-19 | West_2-2 | (0.22 x 0.22) + 10 | Current-Voltage | Single Photon Absorption (SPA) TCT | |
| | West_7-2 | $(0.50 \ge 0.50) + 10$ | Capacitance-Voltage | Source: IR Laser | |
| | $North_2$ | $(0.22 \ge 0.22) + 10$ | Temp (°C). = 24 ± 2 | Source. In Laser | |
| | North_4 | $(0.50 \ge 0.50) + 20$ | Temp (0). -24 ± 2 | Beam size: FWHM 10µm | |
| 3331-16 | North_7-1 | $(0.50 \ge 0.50) + 10$ | | | |
| | East_38 | $(1.0 \ge 1.0) + 20$ | | Temp.(°C): 30, 10, 0, -10, - | |
| | 2 | $(0.22 \ge 0.22) + 10$ | RH (%) = 44 ± 3 | 20, -24 | |
| 3331-13 | 4 | $0.50 \ge 0.50 + 20$ | | | |
| | 7 | $(0.50 \ge 0.50) + 10$ | | | |
| 3331-19 | East_29 | $(1.0 \ge 1.0) + 10$ | LGADs used for the gain measurement | | |
| 3331-19 | $West_7-2$ | $(0.50 \ge 0.50) + 10$ | | | |
| 3331-19 | West_2-1 | $(0.22 \ge 0.22) + 10$ | | | |

Gain Implant Dose: Wafer 3331-19 > Wafer 3331-16 > Wafer 3331-13

Electrical Characteristics



| M. Casado, NIM A, vol. 1032, p. 166628, 2022. |
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| N. Moffat, R. Bates, M. Bullough and N. Tartoni, IEEE, NSS/ |
| N. Moffat and R. Bates , NIM A vol. 1018, p. 165746, 2021 |

| 331-19_West_2-1 | 0.22 x 0.22 | 2.2 | 2.7 | 23 |
|-----------------|---------------|-----|-----|----|
| 331-19_West_7-2 | $0.5 \ge 0.5$ | 3.4 | 4.8 | 41 |

front illumination

- * LGAD with a **higher gain implant dose** is fully depleted at a **higher voltage**.
- * The breakdown voltages are **5-9 times higher** than the **full depletion voltages**.
- * The gain is temperature-dependent, with a 54 % increase for a 50°C change in
- * Gain variation as a function of pixel size is understood; it was due to the reduction

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